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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney's Docket No.:

JG-SU-5224/500577.20073

U.S. Application No.:

10/562,235

Filed: December 22, 2005

International Application No.:

PCT/JP2005/006268

International Filing Date:

MARCH 31, 2005

31 MARCH 2005

Priority Date Claimed:

APRIL 05, 2004

04 APRIL 2004

Title of Invention:

MANUFACTURING METHOD OF SEMICONDUCTOR WAFER AND SEMICONDUCTOR WAFER MANUFACTURED BY THIS METHOD

Applicant(s) for (DO/EO/US):

Syouji NOGAMI, Yukichi HORIOKA, and Shoichi YAMAUCHI

Mail Stop PCT Commissioner For Patents P.O. Box 1450 Alexandria, VA 22313-450

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

SIR:

Applicant herewith submits this Information Disclosure Statement in accordance with the provisions of 37 C.F.R. §§ 1.97 and 1.98, and hereby make of record the following references:

Document Number

Date

Name and/or Country

English Translation and/or Equivalent

2001-196573

07/19/2001

Japan

English Abstract

2003-218037

07/31/2003

Japan

English Abstract

Accompanying this Supplemental Information Disclosure Statement and form PTO-1449 are copies of the documents including English Abstracts. These documents are cited against Japanese Patent Application No. 2004-110634, which is the priority document of this application.

The USPTO waived the requirement under 37 C.F.R. §1.98(a)(2)(i) for submitting copies of US patents and US patent application publications in all U.S. applications filed after June 30, 2003. First pages of US documents only.

This submission is not an admission that the information disclosed in the documents is material to the patentability of the invention disclosed and/or claimed in the above-identified application.

Respectfully submitted,

Dated: December 14, 2006

Reed Smith LLP 599 Lexington Avenue New York, NY 10022-7650

Tel.: (212) 521-5400

JEG:jlw

LIST OF PRIOR ART CITED BY APPLICANT (Filed on December 22, 2005)

Docket No. Applicant(s): Syouji NOGAMI, Yukichi HORIOKA, and Shoichi YAMAUCH				(Filed on De	eçember 22, 2005)				
Application No. 10/552,235 (Int'l Applin No. PCT/JP2004/006268 31MAY05) Group: Unassigned	Docket No.		JG-SU-5224/500577.20073						
December 22, 2005 Examiner: Unassigned	Applica	nt(s):	Syouji NOGA	AMI, Yukichi H	HORIOKA, and Sh	noichi YAM	AUCHI		
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Examiner: Date:

OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

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^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.